### FABRICATION CHART

<table>
<thead>
<tr>
<th>FINISHED THICKNESS</th>
<th>SILSCREEN</th>
<th>SOLDERMASK</th>
<th>FINISHED COPPER WEIGHT</th>
</tr>
</thead>
<tbody>
<tr>
<td></td>
<td>□ 0.031</td>
<td>□ LAYER 1</td>
<td>□ 1 OZ.</td>
</tr>
<tr>
<td></td>
<td>□ 0.062</td>
<td>□ LAYER 1</td>
<td>□ 2 OZ.</td>
</tr>
<tr>
<td></td>
<td>□ 0.093</td>
<td>□ LAYER 2</td>
<td>□ 2 OZ.</td>
</tr>
<tr>
<td></td>
<td>□ 0.125</td>
<td>□ NONE</td>
<td>□ OTHER</td>
</tr>
<tr>
<td></td>
<td></td>
<td></td>
<td></td>
</tr>
<tr>
<td>DESIGN</td>
<td>TRAC/GAP SPACING</td>
<td>LAYER COUNT</td>
<td></td>
</tr>
<tr>
<td>□ SMD</td>
<td>□ 0.010/0.010</td>
<td>□ SINGLE SIDED</td>
<td></td>
</tr>
<tr>
<td>□ THRU-HOLE</td>
<td>□ 0.008/0.008</td>
<td>□ 2 LAYER</td>
<td></td>
</tr>
<tr>
<td>□ MIX</td>
<td>□ 0.008/0.008</td>
<td>□ 4 LAYER</td>
<td></td>
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<tr>
<td></td>
<td></td>
<td>□ 6 LAYER</td>
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<td></td>
<td>□ 8 LAYER</td>
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<td>□ 10 LAYER</td>
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<tr>
<td></td>
<td></td>
<td>□ OTHER</td>
<td></td>
</tr>
</tbody>
</table>

### NOTES: UNLESS OTHERWISE SPECIFIED

1. **MATERIAL:**
   - All materials, including but not limited to base laminate, bonding materials, and soldermask coatings forming the finished printed circuit board shall meet UL-796 requirements and be RoHS compliant and have a flammability of UL94V-0.

2. **BASE LAMINATE:**
   - Plastic sheet, laminated metal clad, one or two sides, base material having type FR-4 or equivalent, W/Tg = 140 Deg C or higher. Minimum composition TEMP (Tg) of 320 Deg C.
   - Glass epoxy resin, copper-clad in accordance with 4-layer stack-up, compliant with lead free process.

3. **SOLDERMASK:**
   - Soldermask over bare copper (SMD) using liquid photo-imageable soldermask in accordance with IPC-SM-840. Color: green. Minor soldermask adjustments to facilitate PCB fab and/or assembly is allowed provided no defects are created to final assembly as a result.

4. **TOLERANCES:**
   - Unless otherwise specified PCB tolerances shall be +/- .003 inches, hole diameters shall be +/- .003 inches.

5. **PLATING:**
   - Holes requiring plating, see hole chart, to have 1 oz. (0.0014) MN. THK. MNL. thick copper.

6. **FINISH:**
   - Plate with RoHS compliant, immersion silver preferred. Immersion tin or Sn/Ag/Cu. with INVA flux, 0.0003" to .0005" thick all exposed areas as coated, no active fluxes are acceptable.

7. **LEGEND:**
   - If required, SilkScreen Legend(s) with white non-conductive epoxy ink.

8. **MARKINGS:**
   - Board must bear vendor’s identification code (etch or white non-conductive ink), location optional.

9. **WORKMANSHIP:**
   - Board is to be manufactured per IPC-A-600 Class 2 requirements or better.

10. **DOCUMENTATION:**
    - PCB vendor is required to return any and all documents supplied or ultimately purchased by Texas Instruments upon completion of purchase order.

11. **DRILL SIZES:**
    - Hole diameters shown are finished sizes after plating unless otherwise noted.

12. **PANEL BORDER:**
    - Any metal in border area including part number, datecode and/or revision letters must be covered with soldermask.

13. **PROCESS CHANGES:**
    - No dimensional, material, or process changes are allowed without prior explicit written permission from Texas Instruments.
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